

**1.0 SCOPE**

This specification documents the detail requirements for space qualified product manufactured on Analog Devices, Inc.'s QML certified line per MIL-PRF-38535 Level V except as modified herein.

The manufacturing flow described in the STANDARD SPACE LEVEL PRODUCTS PROGRAM brochure is to be considered a part of this specification. <http://www.analog.com/aerospace>

This data sheet specifically details the space grade version of this product. A more detailed operational description and a complete data sheet for commercial product grades can be found at [www.analog.com/MUX08](http://www.analog.com/MUX08)

**2.0 Part Number.** The complete part number(s) of this specification follow:

<u>Part Number</u>	<u>Description</u>
MUX08-913Q	Radiation Tested, 8-channel JFET analog multiplexer

**2.1 Package Description:** (see figure 1 for terminal connections)

<u>Letter</u>	<u>Descriptive designator</u>	<u>Case Outline (Lead Finish per MIL-PRF-38535)</u>
Q	GDIP1-T16	16-Lead ceramic dual-in-line package (CERDIP)

**3.0 Absolute Maximum Ratings.** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Positive supply voltage .....	+18V
Negative supply voltage .....	-18V
Logic input voltage .....	(-4V or $V_{EE}$ ) to $V_{CC}$
Analog input voltage .....	$V_{EE} - 20\text{V}$ to $V_{CC} + 20\text{V}$
Maximum current through any pin .....	25mA
Operating Temperature Range .....	$-55^\circ\text{C}$ to $+125^\circ\text{C}$
Storage temperature range .....	$-65^\circ\text{C}$ to $+150^\circ\text{C}$
Power dissipation ( $P_D$ ) .....	500mW
Lead temperature (soldering, 60 seconds) .....	$+300^\circ\text{C}$
Junction temperature ( $T_J$ ) .....	$+150^\circ\text{C}$
Thermal resistance, junction to case ( $\Theta_{JC}$ ) .....	See MIL-STD-1835
Thermal resistance, Junction to ambient ( $\Theta_{JA}$ )	
Case Q .....	$91^\circ\text{C/W}$
Case RC .....	$110^\circ\text{C/W}$

		Package
		Q
Terminal Number	1	A <sub>0</sub>
	2	ENABLE
	3	V <sub>EE</sub>
	4	S1
	5	S2
	6	S3
	7	S4
	8	DRAIN
	9	S8
	10	S7
	11	S6
	12	S5
	13	V <sub>CC</sub>
	14	GND
	15	A <sub>2</sub>
	16	A <sub>1</sub>

Figure 1 - Terminal connections.

A2	A1	A0	ENABLE	"On" Channel
X	X	X	L	None
L	L	L	H	1
L	L	H	H	2
L	H	L	H	3
L	H	H	H	4
H	L	L	H	5
H	L	H	H	6
H	H	L	H	7
H	H	H	H	8

Figure 2 - Truth Table

4.0 Electrical Table:

Parameter See notes at end of table	Symbol	Conditions $V_S = \pm 15V$ unless otherwise specified	Sub-group	Limit Min	Limit Max	Units
Positive supply current	$I_{CC}$		1		12	mA
			2, 3		15	
Negative supply current	$I_{EE}$		1	-3.8		
			2, 3	-5		
Digital input current	$I_{IN}$	$V_{IN} = 0.4V$ to 15V	1		$\pm 10$	$\mu A$
			2, 3		$\pm 20$	
Digital "0" enable current	$I_{IN(EN)}$	$V_{IN(EN)} = 0.4V$	1		$\pm 10$	
			2, 3		$\pm 20$	
"ON" resistance	$R_{ON}$	$-10V < V_S < +10V, I_S = 200 \mu A$	1		300	$\Omega$
			2, 3		400	
"ON" resistance change with change in source voltage <u>1/</u>	$\Delta R_{ON} / \Delta V_S$	$-10V < V_S < +10V, I_S = 200 \mu A$	1		5	%
			2		7	
			3		6	
RON match between switches <u>4/</u>	$R_{ON MATCH}$	$V_S = 0V, I_S = 200 \mu A$	1		15	
			2		20	
			3		18	
Analog voltage range <u>1/</u>	$V_A$		1, 2, 3	$\pm 10$		V
Source current (OFF)	$I_{S(OFF)}$	$V_S = +10V, V_D = -10V$ <u>3/</u>	$V_{IL} = 0.8V$	1, 3	$\pm 1$	nA
Drain current (OFF)	$I_{D(OFF)}$		$V_{IL} = 0.7V$	2	$\pm 25$	
			$V_{IL} = 0.8V$	1, 3	$\pm 1$	
			$V_{IL} = 0.7V$	2	$\pm 100$	
Leakage current, switch (ON)	$I_{S(ON)} + I_{D(ON)}$	$V_S = V_D = +10V, V_{IH} = 2V$ <u>3/</u>		1, 3	$\pm 1$	
			2	$\pm 100$		
Digital "0" input voltage <u>1/</u>	$V_{IL}$			1, 3	0.8	V
				2	0.7	
Digital "1" input voltage <u>1/</u>	$V_{IH}$		1, 2, 3	2.0		
Functional testes <u>2/</u>			1, 2, 3	--	--	
Switching time	$t_{PHL}$	$V_{S1} = +10V, V_{S8} = -10V, R_L = 10M\Omega, C_L = 10pF$ , see fig. 4 & 5	9		2.1	$\mu S$
	$t_{PLH}$		10, 11		3.5	
Enable delay "ON"	$t_{ON(EN)}$	$V_{S1} = -10V, C_L = 10pF, R_L = 1K\Omega$ , see fig. 5 & 6	9		2.0	
			10, 11		3.0	
Enable delay "OFF"	$t_{OFF(EN)}$		9		0.4	
			10, 11		1.0	
Break-before-make delay	$t_{OPEN}$	$V_{S1} = V_{S8} = -1V$ , see fig. 5 & 7	9	0.1		

TABLE I NOTES:

- 1/ Guaranteed, if not tested, to the specified limits
- 2/ Verified by leakage tests
- 3/ Conditions applied to leakage tests insure worst case leakages.
- 4/  $R_{ON MATCH}$  specified as a percentage of  $R_{AVERAGE}$  where:

$$R_{AVERAGE} = \frac{1}{N} \sum_{i=1}^N R_i$$

with N = number of channels, Ri = each channel's "ON" resistance.

**4.1 Electrical Test Requirements:**

Table II	
Test Requirements	Subgroups (in accordance with MIL-PRF-38535, Table III)
Interim Electrical Parameters	1
Final Electrical Parameters	1, 2, 3, 9 <u>1/</u> <u>2/</u>
Group A Test Requirements	1, 2, 3, 9, 10, 11
Group C end-point electrical parameters	1 <u>2/</u>
Group D end-point electrical parameters	1
Group E end-point electrical parameters	1

1/ PDA applies to Subgroup 1 only. Delta limits are excluded from PDA  
2/ See table III for delta limits.

**4.2 Table III. Burn-in test delta limits.**

Table III			
TEST TITLE	ENDPOINT LIMIT	DELTA LIMIT	UNITS
R <sub>ON</sub>	300	50	Ohm

**5.0 Life Test/Burn-In Circuit:**

- 5.1 HTRB is not applicable for this drawing.
- 5.2 Burn-in is per MIL-STD-883 Method 1015 test condition B.
- 5.3 Steady state life test is per MIL-STD-883 Method 1005.

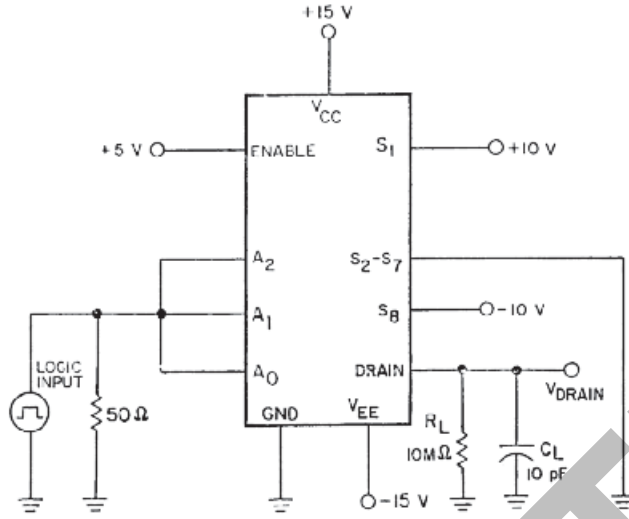


Figure 4 - Transition time test circuit

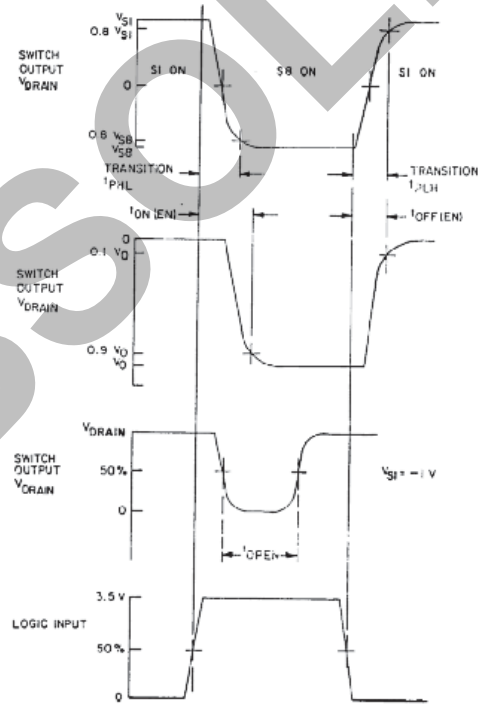


Figure 5 - Switching time waveforms

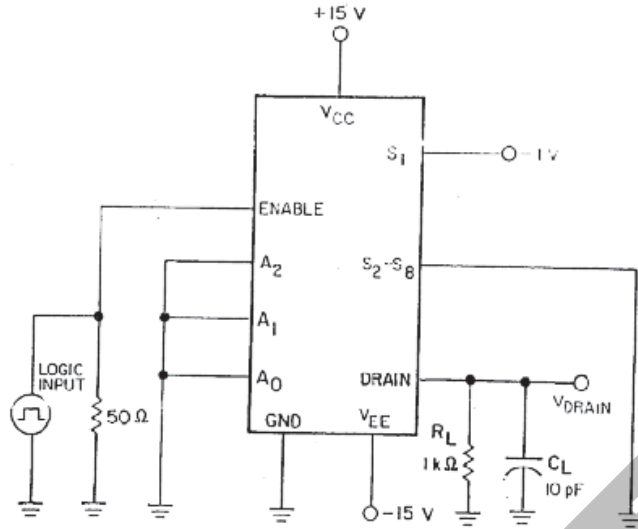


Figure 6 - Enable delay time test circuit

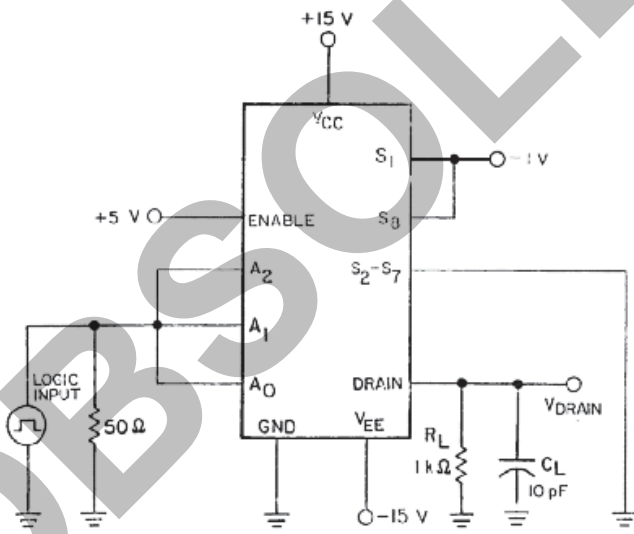


Figure 7 - Break-before-make test circuit

Rev	Description of Change	Date
A	Initiate	06-30-2000
B	Update web address	02-18-2002
C	Update web address. Remove Burn-In and rad bias circuits.	05-15-2003
D	Update header/footer & add to 1.0 Scope description	02-22-2008
E	Add Operating Temperature Range -55°C to +125°C to 3.0 Absolute Max Ratings	03-31-2008
F	Remove obsolete part numbers and update ASD to ADI Standard	11-08-2011

OBSOLETE